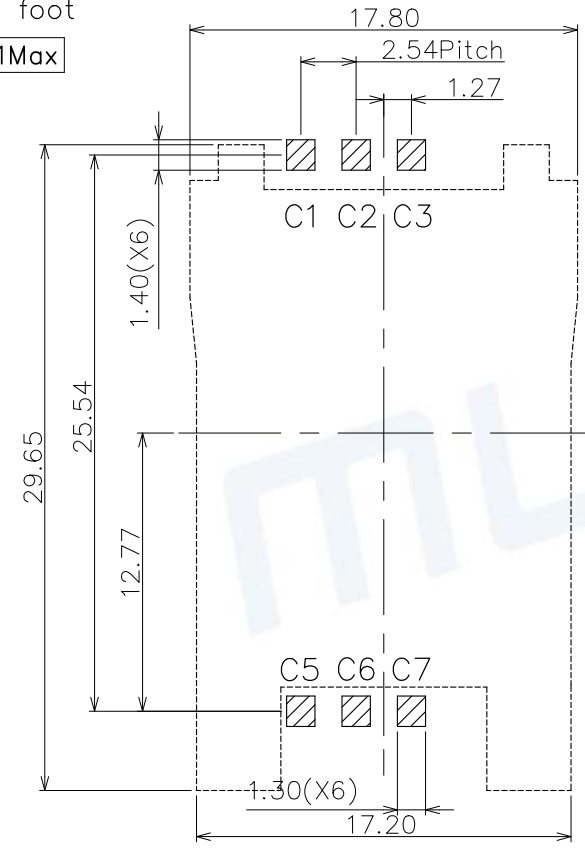
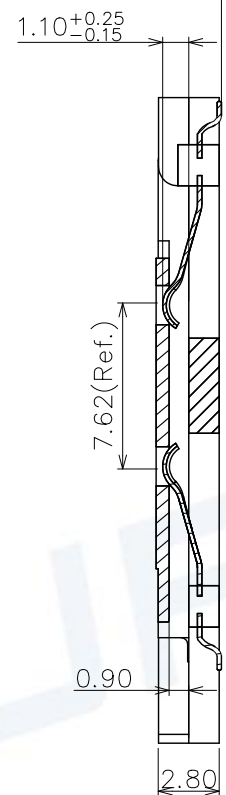
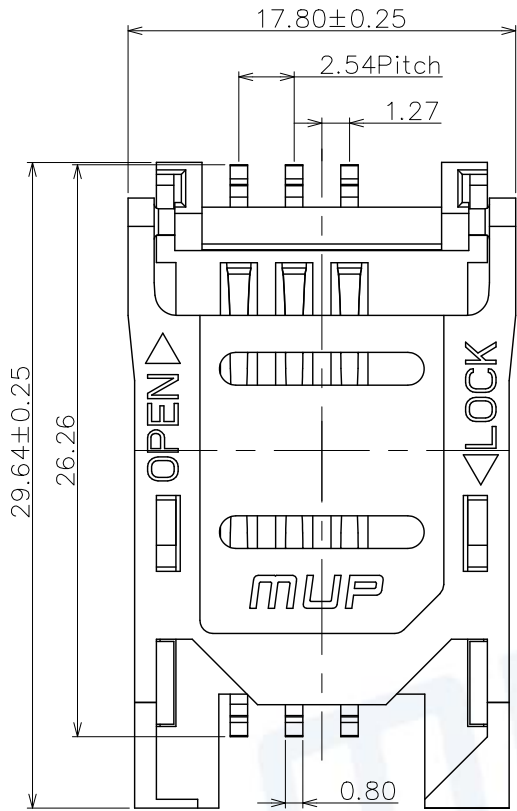


| REV. | DESCRIPTION OF REVISIONS | APPR. | DRAW. | RELEASE | DATE |
|------|--------------------------|-------|-------|---------|-----------|
| X1 | 新开 | Simon | Jimmy | Lynn | 2006.3.10 |
| X2 | 增加主体塑性变形尺寸 | Simon | huabo | Lynn | 2020.9.17 |

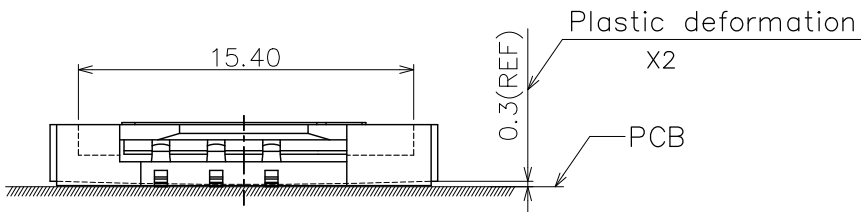
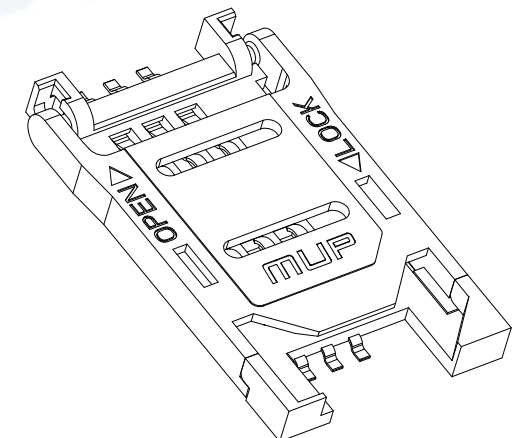
Flatness of solder foot

0.1Max



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

- TECHNICAL CHARACTERISTICS**
- General Characteristics**
Dimensions: 29.65X17.80WX2.80H mm
Weight: Approx1.14±0.20g
Durability: 5,000 cycles min.
 - Electrical Characteristics**
Contact resistance: 50mΩ typical,100mΩ max
Insulation resistance: >1000MΩ/500V DC
 - Solderability**
Vapor phase: 215°C,30sec.Max
IR reflow: 250°C,5sec.Max
Manual soldering: 370°C,3sec.Max
 - Environmental Characteristics**
Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH



| ITEM | PART NAME | Q'TY | MATERIAL | FINISH |
|------|--------------|------|-----------------------|-----------------------------|
| 1 | BASE | 1 | Hi-temp Thermoplastic | Natural color UL94V-0 |
| 2 | COVER | 1 | Hi-temp Thermoplastic | Natural color UL94V-0 |
| 3 | DATA CONTACT | 6 | Copper Alloy | Contact area:15u" Au plated |

Unless otherwise specified, other tolerance are:

| | | | |
|-------|-------|--------|-----|
| X | ±0.35 | X' | ±5' |
| X.X | ±0.25 | X.X' | ±4' |
| X.XX | ±0.15 | X.XX' | ±3' |
| X.XXX | ±0.10 | X.XXX' | ±2' |

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**
MODEL NO: **MUP C713-23**
TYPE: **H2.8 without post 6p**

| | | | | | | | |
|------------------|------|-------|----------|-------|-------------|----------|------------------|
| PROJ. | UNIT | SCALE | DRAWN | Zoey | Mar.10.2006 | DWG NO.: | DWG-MUP-C713-023 |
| | mm | 1:1 | CHECKED | Jimmy | Mar.10.2006 | SHEET | 1/1 |
| CUSTOMER DRAWING | | | APPROVAL | Jun | Mar.10.2006 | REVISION | X2 |

